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Part Number: [0545480871](#)
Status: **Active**
Overview: [ffc_fpc_smt](#)
Description: 0.50mm (.020") Pitch FFC/FPC Connector, 1.20mm (.047") Height, Right Angle, SMT, ZIF, Bottom Contact Style, 8 Circuits, Lead-free, Gold (Au) Plating

Documents:

3D Model	Product Specification PS-54548-039 (PDF)
Drawing (PDF)	RoHS Certificate of Compliance (PDF)

General

Product Family	FFC/FPC Connectors
Series	54548
Overview	ffc_fpc_smt
Product Name	N/A

Physical

Circuits (Loaded)	8
Contact Position	Bottom
Durability (mating cycles max)	20
Entry Angle	90° Angle
Mated Height (in)	0.047 In
Mated Height (mm)	1.20 mm
Material - Metal	Phosphor Bronze
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Number of Rows	1
Orientation	Right Angle
PCB Locator	No
PCB Retention	Yes
Packaging Type	Embossed Tape on Reel
Pitch - Mating Interface (in)	0.020 In
Pitch - Mating Interface (mm)	0.50 mm
Polarized to PCB	Yes
Stackable	No
Temperature Range - Operating	-20°C to +85°C
Termination Interface: Style	Surface Mount
Wire/Cable Type	FFC/FPC

Electrical

Current - Maximum per Contact	0.5A
Voltage - Maximum	50V

Material Info

Reference - Drawing Numbers

Packaging Specification	SPK-54548-001
Product Specification	PS-54548-039, RPS-54548-085, RPS-54548-097, RPS-54548-099, RPS-54548-102
Sales Drawing	SD-54548-039, SD-54548-040

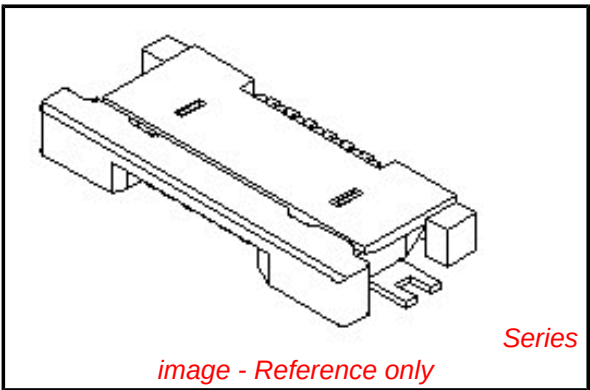


image - Reference only

EU RoHS

**ELV and RoHS
Compliant**
REACH SVHC
Not Reviewed
**Halogen-Free
Status**

China RoHS

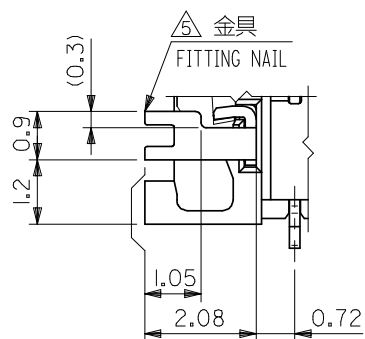
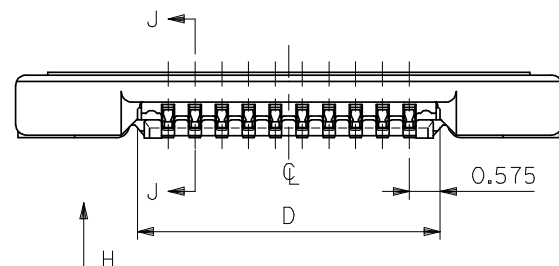
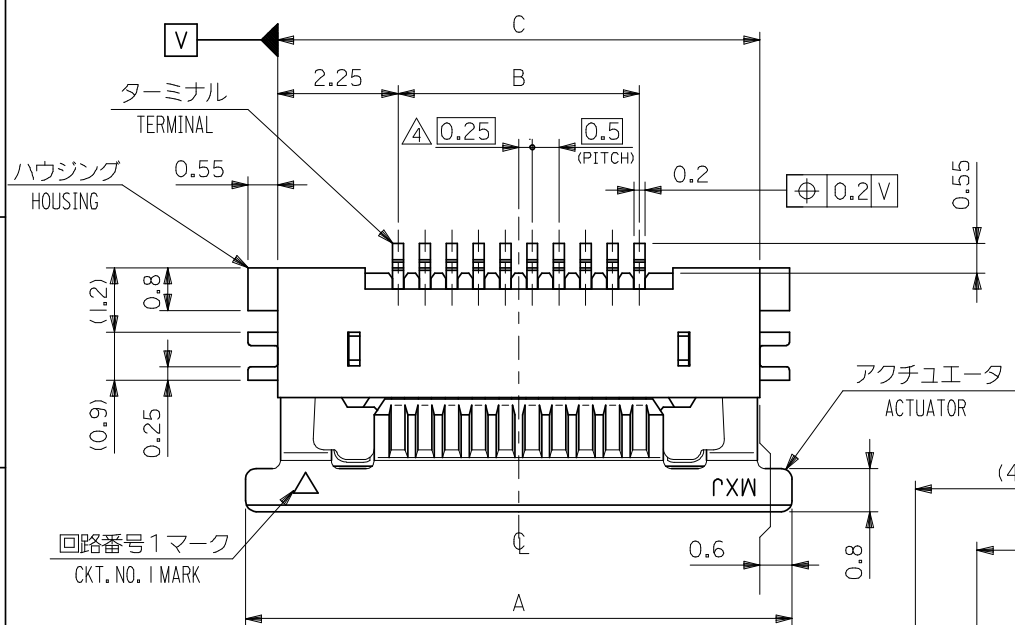


**Need more information on product
environmental compliance?**

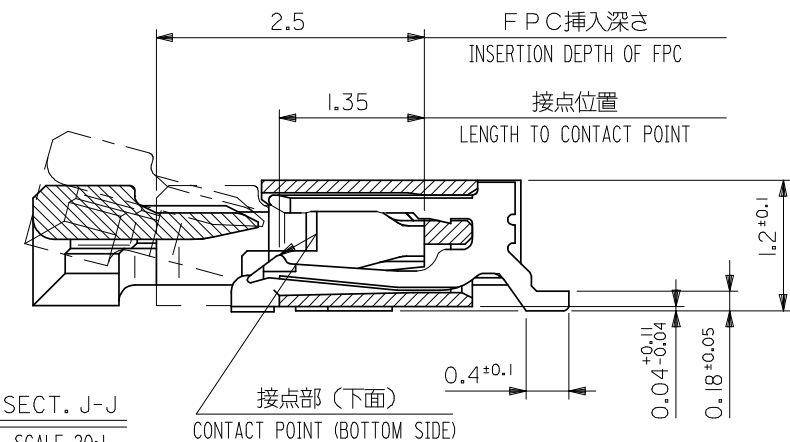
Email productcompliance@molex.com
For a multiple part number RoHS Certificate of
Compliance, [click here](#)

Please visit the [Contact Us](#) section for any
non-product compliance questions.

Search Parts in this Series
[54548Series](#)



VIEW H



SECT. J-J
SCALE 20:1

0.28±0.03	13.65	17.0	12.5	18.2	54548-2671	54548-2629	26
	12.65	16.0	11.5	17.2	54548-2471	54548-2429	24
0.3±0.03	12.15	15.5	11.0	16.7	54548-2371	54548-2329	23
	11.65	15.0	10.5	16.2	54548-2271	54548-2229	22
	11.15	14.5	10.0	15.7	54548-2171	54548-2129	21
	10.65	14.0	9.5	15.2	54548-2071	54548-2029	20
	10.15	13.5	9.0	14.7	54548-1971	54548-1929	19
	9.65	13.0	8.5	14.2	54548-1871	54548-1829	18
	9.15	12.5	8.0	13.7	54548-1771	54548-1729	17
	8.65	12.0	7.5	13.2	54548-1671	54548-1629	16
	8.15	11.5	7.0	12.7	54548-1571	54548-1529	15
	7.65	11.0	6.5	12.2	54548-1471	54548-1429	14
	7.15	10.5	6.0	11.7	54548-1371	54548-1329	13
	6.65	10.0	5.5	11.2	54548-1271	54548-1229	12
	6.15	9.5	5.0	10.7	54548-1171	54548-1129	11
	5.65	9.0	4.5	10.2	54548-1071	54548-1029	10
	5.15	8.5	4.0	9.7	54548-0971	54548-0929	9
	4.65	8.0	3.5	9.2	54548-0871	54548-0829	8
	4.15	7.5	3.0	8.7	54548-0771	54548-0729	7
	3.65	7.0	2.5	8.2	54548-0671	54548-0629	6
	3.15	6.5	2.0	7.7	54548-0571	54548-0529	5
	2.65	6.0	1.5	7.2	54548-0471	54548-0429	4
FPC THICKNESS	D	C	B	A	EMBOSSD TAPE ORDER No. オーダー番号	製品番号 MATERIAL No.	極数 Ck+

54548-**29	MODEL No.
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DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION
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0.5 FPC CONN ZIF HSG
ASSY FOR SMT RA BTM CONT
-LEAD FREE-

MOLEX INCORPORATED

DOCUMENT NO. SD-54548-039	SHEET NO. 1 OF 2
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THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

REVISED	EC NO: J2008-4048	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)	
	DRWN:WABEI		10 UNDER	± 0.2
	CH'KD: THIRUYAMA		10 OVER 30 UNDER	± 0.25
	APPR: NUKITA		30 OVER	± 0.3
			ANGULAR	± 3 °
		REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

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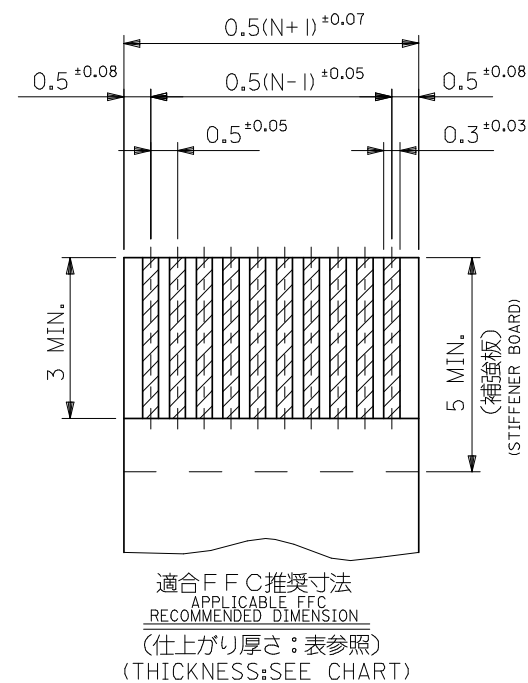
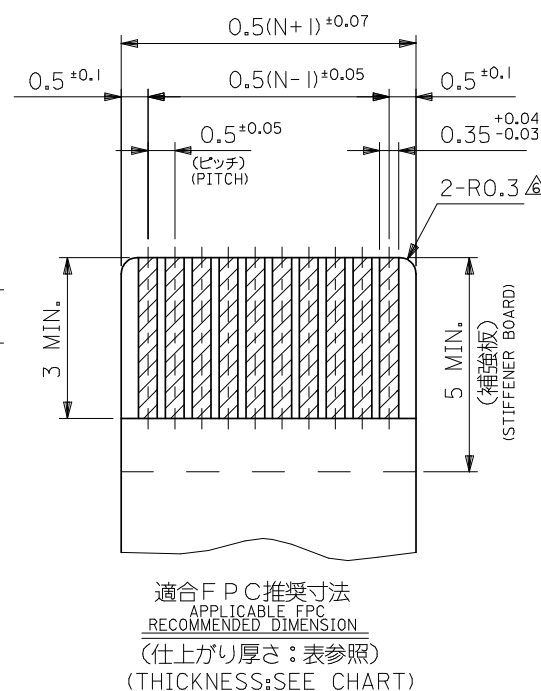
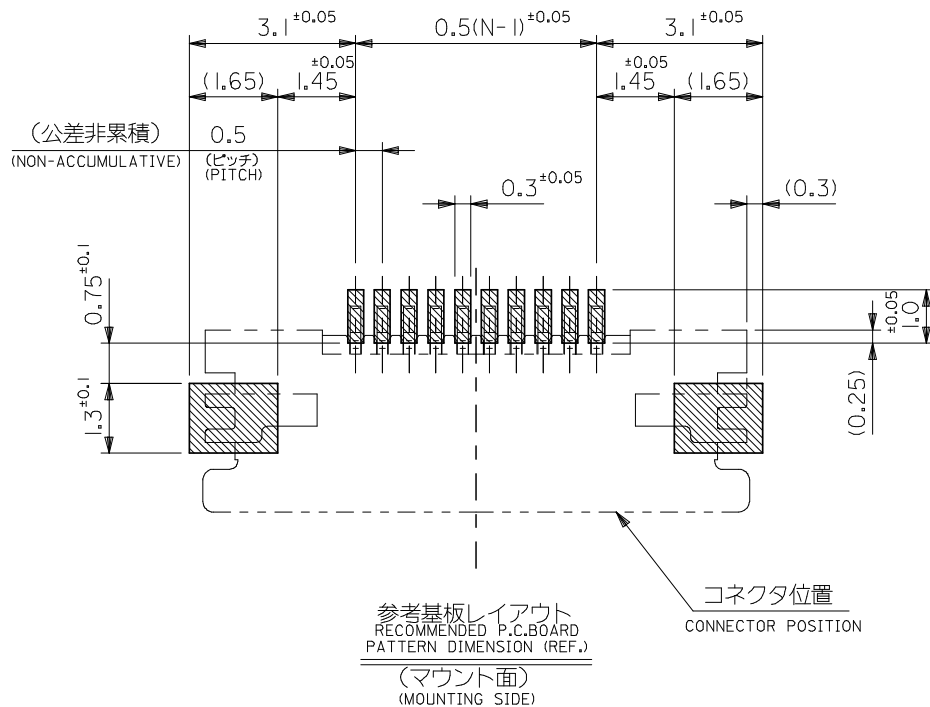
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注記 NOTES

I. 使用材料 MATERIAL

ハウジング : LCP, UL94V-0
ハウジング
アクチュエータ : PPS, UL94V-0
アクチュエータ
ターミナル : リン青銅 (t=0.2)
ターミナル
メッキ : PHOSPOR BRONZE
メッキ
接点部 : 金メッキ
CONTACT PORTION : GOLD PLATING
テール部 : 鍍メッキ
SOLDERING PORTION : TIN OVER PLATING
下地 : ニッケルメッキ
UNDER PLATING: NICKEL PLATING
金具 : リン青銅、鍍メッキ (t=0.2)
FITTING NAIL : PHOSPOR BRONZE, TIN PLATING
下地 : ニッケルメッキ
UNDER PLATING: NICKEL PLATING

2. エンボステープ梱包時は、アクチュエータがロックした状態とする。
IN THE PACKAGE, ACTUATOR OF PART NO. 54548-**-29 SHOULD BE LOCKED.
3. ソルダータール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 Z に対し上方向 0 MAX.、下方向 0.15 MAX.、とし
相互のバツキ量は 0.1 MAX. とする。
MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM Z
UPPER DIRECTION: 0 MAX., LOWER DIRECTION: 0.15 MAX.
OFFSET BETWEEN UPPER AND LOWER 0.1 MAX.

4. 偶数極に適用。
APPLY FOR EVEN CIRCUIT.

5. パターンはくり止め用金具
FITTING NAIL FOR PREVENTION OF PEELING OF P.C.B. PATTERN.
6. RO.3 は FPC 導体部にかからないこと
RO.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.
7. 本製品は 54548-**-21 の鉛フリー (部分金メッキ) 品である。
THIS PRODUCT IS LEAD FREE OF 54548-**-21 (SELECTIVE GOLD).
8. N: 極数 N: CIRCUIT.

FPC/FFC について:

打ち抜き方向は導体側から補強板側を推奨します。
導体部については軟銅箔 35 μm または 50 μm を推奨します。

ABOUT FPC/FFC

RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.
RECOMMENDED CONDUCTOR SPEC :
THICKNESS OF SOFT COPPER FOIL : 35 MICROMETER OR 50 MICROMETER.

FPC について:

補強フィルム材質はポリイミドを推奨します。ベースフィルムは 25 μm を推奨します。
接着剤は熱硬化接着剤を推奨します。
尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様、お願い致します。

ABOUT FPC

RECOMMENDED MATERIAL/THICKNESS.
STIFFENER FILM : POLYIMIDE
BASE FILM THICKNESS : 25 μm
BONDING AGENT : THERMOSETTING BONDING AGENT
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON THE CONTACT AREA BECAUSE THE EXTRA ADHESIVE MAY CAUSE THE DEFECT IN ELECTRICAL CONTINUITY.

REVISED EC NO: J2008-4048 DRWN:WABEI CHKD:THARUYAMA APPR:NUKITA	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC		MODEL NO. THIRD ANGLE PROJECTION
		10 UNDER	± 0.2	DRAWN BY HSHIMABUKURO	DATE '04/02/10	TITLE 0.5 FPC CONN ZIF HSG ASSY FOR SMT RA BTM CONT -LEAD FREE-			
		10 OVER 30 UNDER	± 0.25	CHECKED BY KTOJO	DATE '04/02/10				
		30 OVER	± 0.3	APPROVED BY MSASAO	DATE '04/02/10	molex MOLEX INCORPORATED			
		ANGULAR ±3 °	MATERIAL NO. SEE SHEET 1		DOCUMENT NO. SD-54548-039				
	REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

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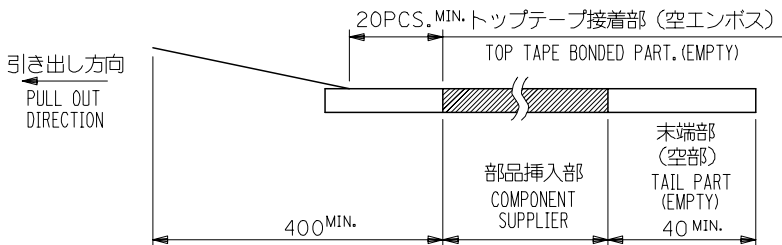
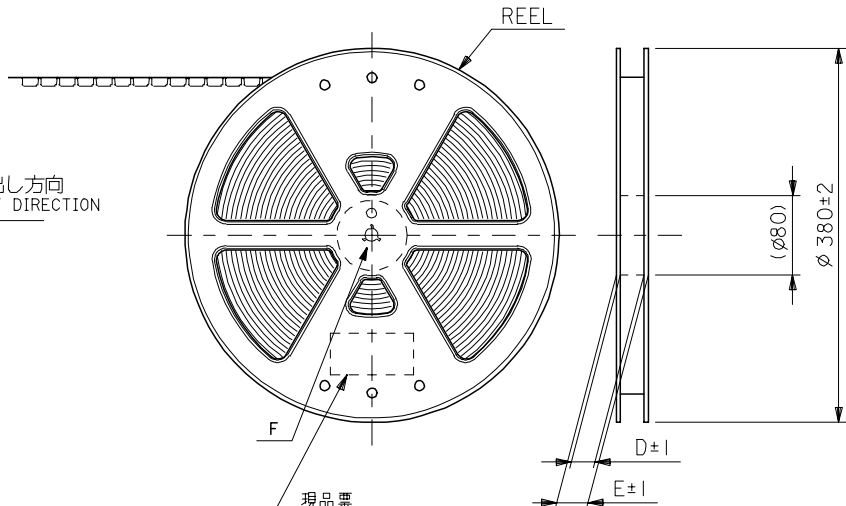
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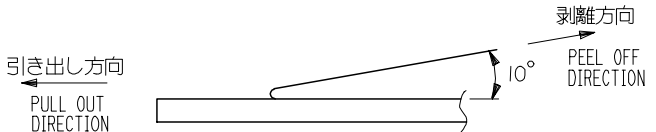
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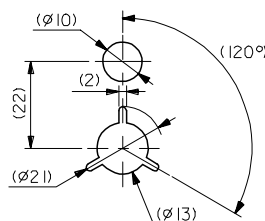
1. 製品詳細寸法については図面 SD-54548-039 を参照下さい。
RE DETAILED DIMENSION, SEE SD-54548-039
2. 梱包数量：3000個/リール
NUMBER OF CONNECTORS : 3000PCS/REEL
3. リードテープ長さ LEAD TAPE LENGTH



4. トップテープの剥離強度：0.1N ～ 1.3N(10gf ～ 130gf)
(剥離方向は下図参照)
尚、本規格値は出荷時に適用。(但し、輸送時に剥離が発生しないこと。)
PEELING OFF FORCE OF TOP TAPE : 0.1N ～ 1.3N(10gf ～ 130gf)
(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
PEEL OFF SHOULD NOT BE ALLOWED , DURING TRANSPORTATION.



5. 材料(MATERIAL)
キャリアテープ(CARRIER TAPE) : ポリプロピレン(POLYPROPYLENE)
トップテープ(TOPTAPE) : PET , PE , PEF
リール(REEL) : ポリスチレン (P.S) <リサイクル材を含む>
POLYSTYRENE(PS) <RECYCLE MATERIAL CONTAINED>
6. 本製品は 54548-**91 の鉛フリー(部分金メッキ)品である。
THIS PRODUCT IS LEAD FREE OF 54548-**91 (SELECTIVE GOLD).



DETAIL F

REVISED EC NO: J2006-3468 DRAWN: NABEI CHKD: KTOYODA APPR: NUKITA		DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE ---	54548-***71		MODEL No.		
					MM ONLY			DESIGN UNITS METRIC		THIRD ANGLE PROJECTION		
			10 UNDER	±0.2	DRAWN BY HSHIMABUKURO		DATE '04/02/10		TITLE 0.5 FPC CONN ZIF HSG ASSY RA BOTTOM CONTACT -LEAD FREE-			
			10 OVER 30 UNDER	±0.25	CHECKED BY KTOJO		DATE '04/02/10					
30 OVER	±0.3	APPROVED BY MSASAO		DATE '04/02/10		MOLEX MOLEX INCORPORATED						
J		REV	ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.			
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-54548-040		1 OF 4			
			SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

